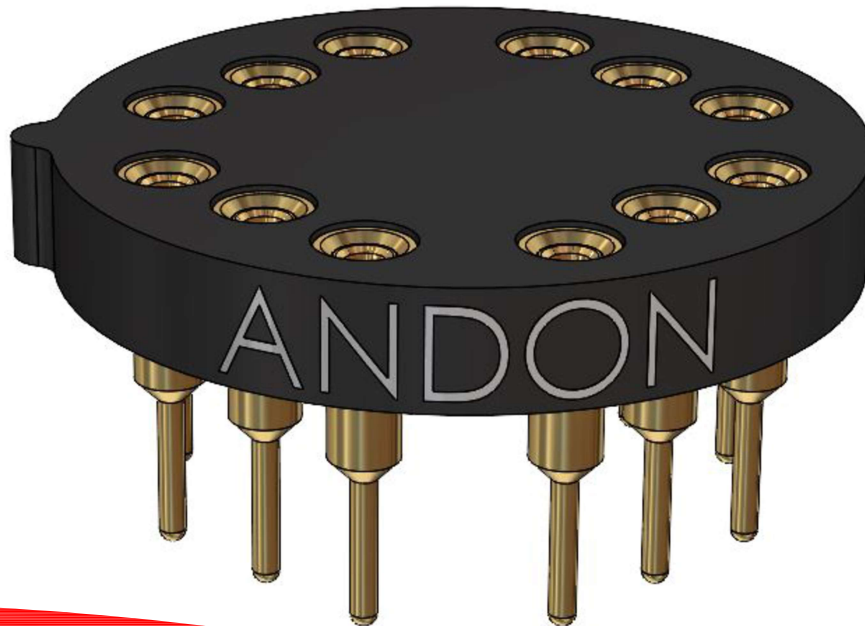




High-Reliability Optoelectronic Sockets for Analog Modules, Inc.



Featuring Andon's Unique SenstacTM Contact

Analog Modules, Inc.						
Analog Modules, Inc. Model Number	Andon Part Number Replace "XXX" with Terminal Type	Terminal Type		Pin Ø [in]	Figure Number	Page Number
		Thru-Hole	Surface Mount			
523-1-A	C10-308-04-01-XXX-R27-L14	01S	93S	.018	1	1
524	C10-308-04-01-XXX-R27-L14	01S	93S	.018	1	1
753A	R790-1212-03T-XXX-R27-L14	01S	93S	.018	5	2
755A	R400-SP12-01T-XXX-R27-L14	01S	93S	.018	2	2
755A-03.1	R400-SP12-01T-XXX-R27-L14	01S	93S	.018	2	2
755A-04	R400-SP12-01T-XXX-R27-L14	01S	93S	.018	2	2
755A-04.1	R400-SP12-01T-XXX-R27-L14	01S	93S	.018	2	2
756	R400-SP12-01T-XXX-R27-L14	01S	93S	.018	2	2
758-03.1	101-628-XXX-R27-L14	01S	93S	.018	6	2
758-04.1	101-628-XXX-R27-L14	01S	93S	.018	6	2
758A-03.1	101-628-XXX-R27-L14	01S	93S	.018	6	2
758A-04.1	101-628-XXX-R27-L14	01S	93S	.018	6	2
758B-04.1	101-628-XXX-R27-L14	01S	93S	.018	6	2
759A	R400-SP06-01T-XXX-R27-L14	01S	93S	.018	4	2
7510-1	R400-SP09-01T-XXX-R27-L14	01S	93S	.018	3	2
7511B-2-04	R400-SP12-01T-XXX-R27-L14	01S	93S	.018	2	2
758-04	101-628-XXX-R27-L14	01S	93S	.018	6	2
758-03	101-628-XXX-R27-L14	01S	93S	.018	6	2
758.1	101-628-XXX-R27-L14	01S	93S	.018	6	2

See last page for other mounting types including low profile options.
Heat sink socket available to reduce heat and noise. Contact Andon for details.

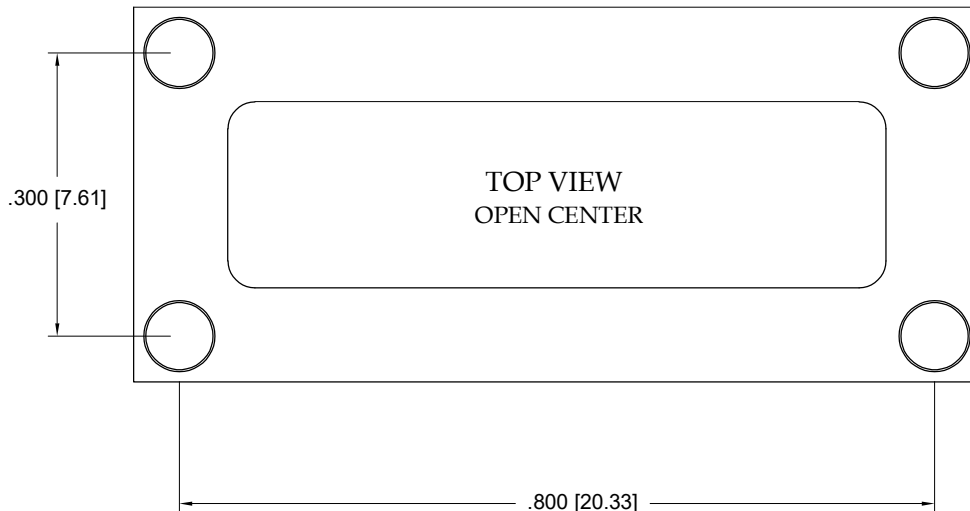


Fig. 1
Thru-Hole: C10-308-04-01-01S-R27-L14
Surface Mount: C10-308-04-01-93S-R27-L14

INTERCONNECTION SPECIALISTS

Analog Modules Inc. Continued

Top View Shown
Units: in [mm]

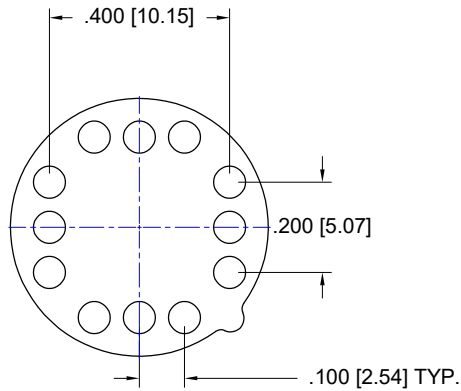


Fig. 2
Thru-Hole: R400-SP12-01T-01S-R27-L14
Surface Mount: R400-SP12-01T-93S-R27-L14

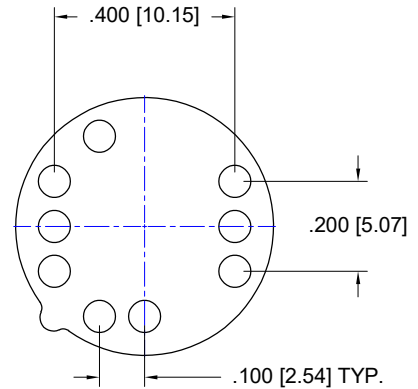


Fig. 3
Thru-Hole: R400-SP09-01T-01S-R27-L14
Surface Mount: R400-SP09-01T-93S-R27-L14

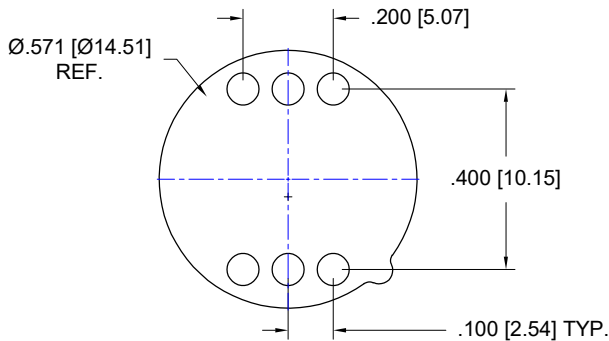


Fig. 4
Thru-Hole: R400-SP06-01T-01S-R27-L14
Surface Mount: R400-SP06-01T-93S-R27-L14

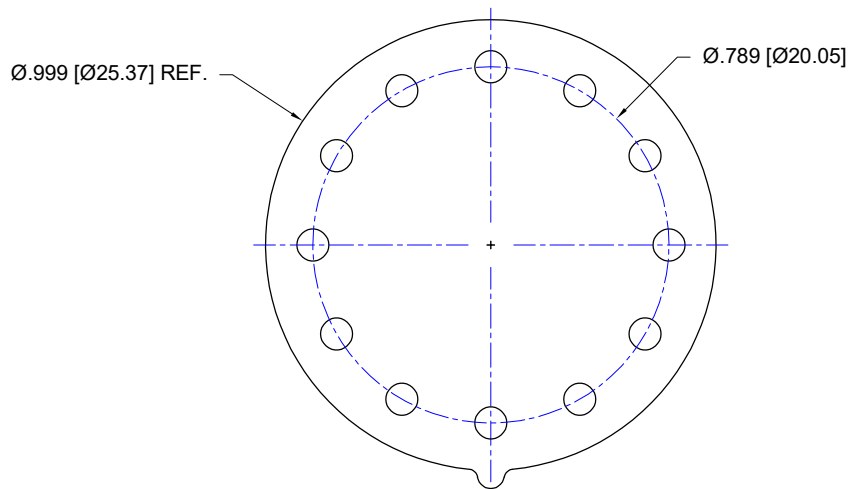


Fig. 5
Thru-Hole: R790-1212-03T-01S-R27-L14
Surface Mount: R790-1212-03T-93S-R27-L14

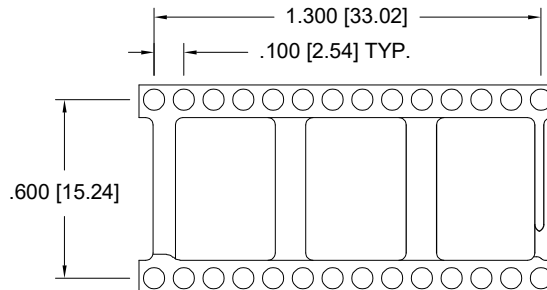
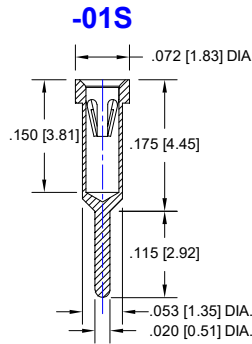


Fig. 6
Thru-Hole: 101-628-01S-R27-L14
Surface Mount: 101-628-93S-R27-L14

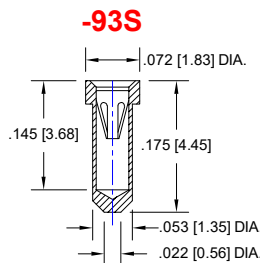
Analog Modules Inc. Continued

Units: in [mm]

THRU HOLE OPTION



SURFACE MOUNT OPTION



Technical Information

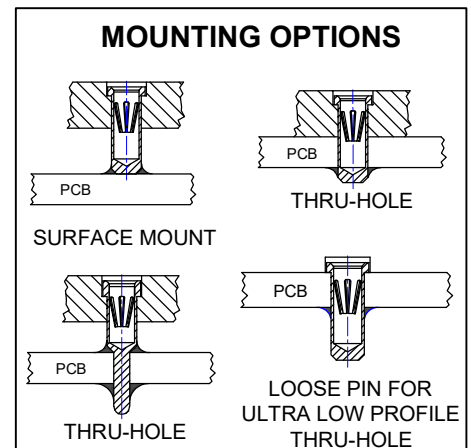
Material:

Insulator: Hi-Temp UL 94V-O
 Terminal: Brass, per ASTM-B16
 Contact: BeCu, Per ASTM-B194

Plating: RoHS COMPLIANT
R27 TERMINAL: GOLD / CONTACT: GOLD
OTHER PLATINGS AVAILABLE

Terminal Acceptance and Forces

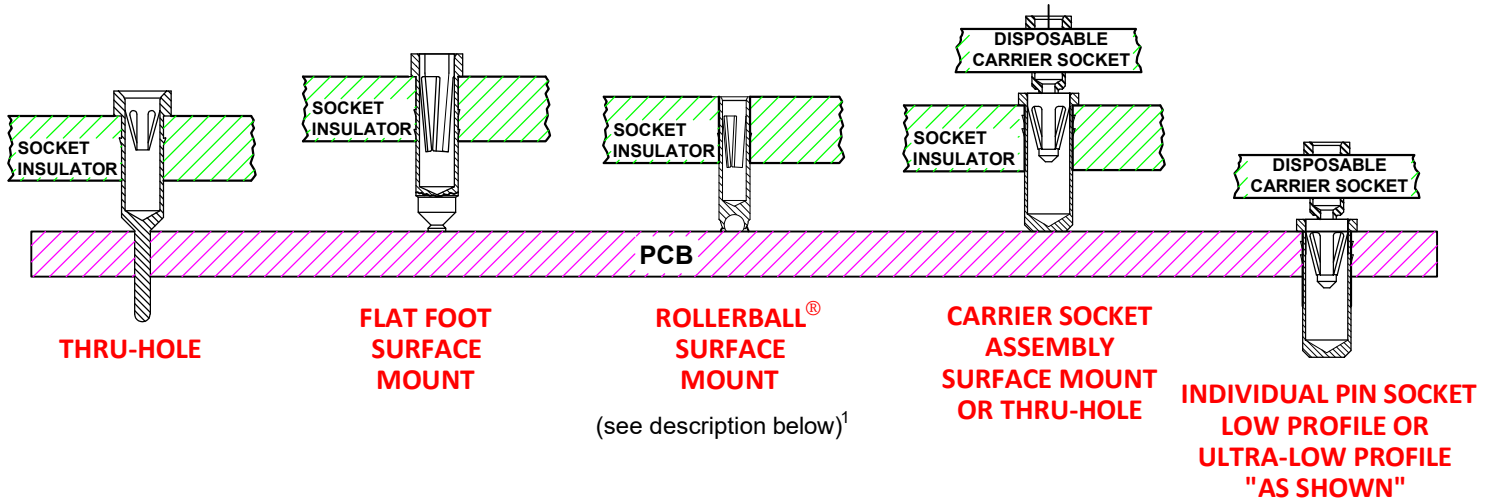
Thru Hole Terminals				Surface Mount Terminals			
Thru Hole Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force	Surface Mount Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force
-01S	Ø.018 [Ø0.46]	9.0 oz AVG	2.0 oz Min	-93S	Ø.018 [Ø0.46]	9.0 oz AVG	2.0 oz Min



Andon Proprietary Information
RoHS Compliant

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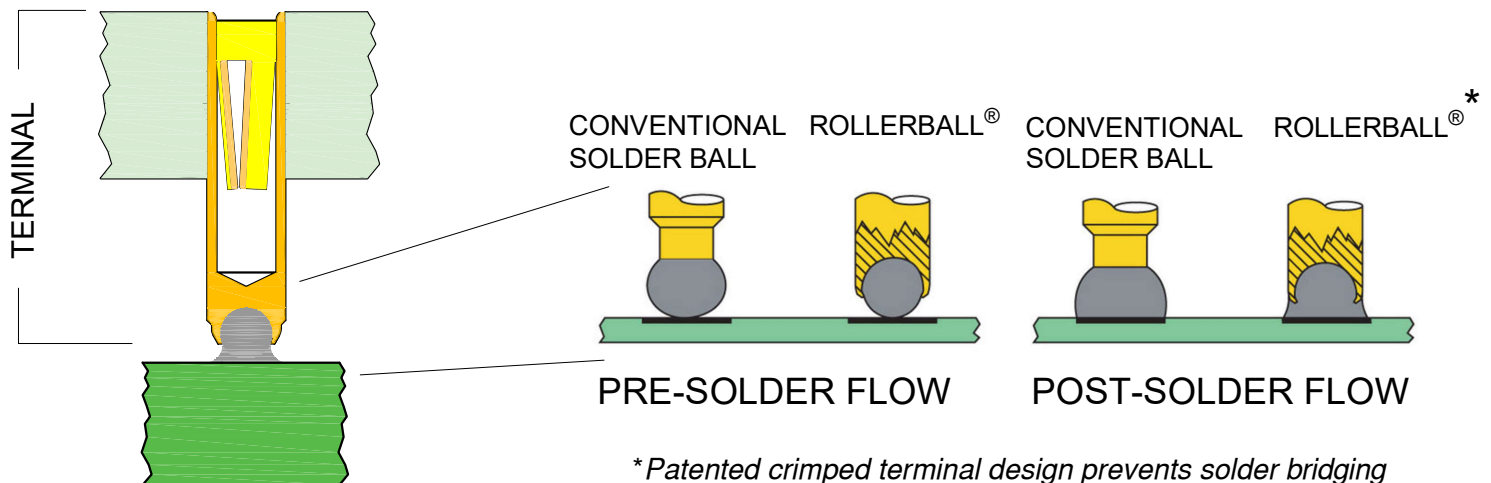
*Sockets are not drawn to scale Analog Modules, Inc. 05/13/2026



¹Andon's patented Rollerball® socket terminal option provides more accurate soldering, a stronger connection, and improved electrical connectivity - especially under shock and vibration - than other solder ball terminal designs. Better yet, it can enable you to avoid expensive rework and scrap - especially with larger PCBs where coplanarity is an inherent challenge.

The bottom of these terminals has a radiused hole, to prevent gas entrapment. The terminal is crimped over the solder ball beyond its hemisphere, encapsulating it - leaving just enough of the solder ball exposed to provide sufficient solder without the solder bridging common in conventional solder ball terminal designs.

With this unique design, the critical distance between the terminal and the PC board pad is typically reduced from .036"-.040" to .018"-.022". As such, the solder becomes part of the "anchor" cross-section - providing additional mechanical strength to the connection, as well as improved electrical connectivity. Because it also provides controlled dispersion of solder, this encapsulated solder ball reduces the risk of solder bridging inherent in conventional solder ball terminal designs.



For fast, accurate placement of SIP sockets and ultra-low profile terminals

Phase 1:
Receive Carrier Assemblies designed to your pin layout.



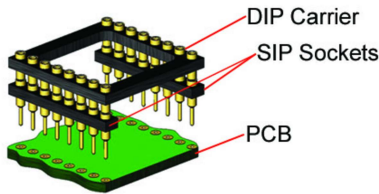
Phase 2:
Place carrier assemblies onto PCB; run through your soldering process.



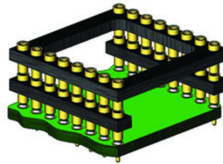
Phase 3:
Remove carrier and plug in your device; discard carrier or send back to our factory for reloading.

DIP

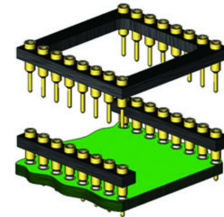
Before Soldering



During Soldering

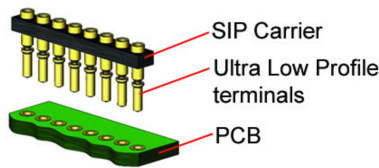


After Soldering

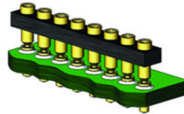


ULTRA-LOW PROFILE SIP

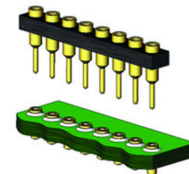
Before Soldering



During Soldering

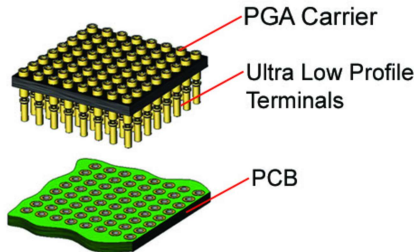


After Soldering

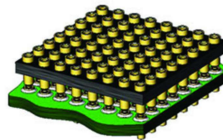


ULTRA-LOW PROFILE PGA

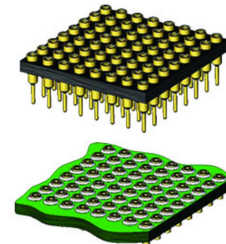
Before Soldering



During Soldering

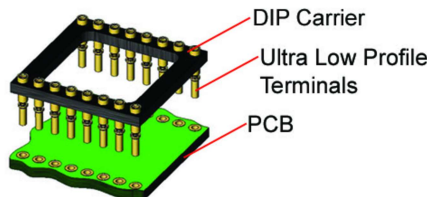


After Soldering

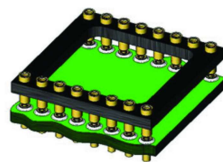


ULTRA LOW PROFILE DIP

Before Soldering



During Soldering



After Soldering

